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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Cobbley et al.

Docket No: 150.00720103

Patent No.: 6,699,928 B2

Issued: March 2, 2004

Title: ADHESIVE COMPOSITION FOR USE IN PACKAGING APPLICATIONS

Attention Certificate of Correction Branch  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting the following documents along with this Transmittal Sheet (which is submitted in triplicate):

X An itemized return postcard.

X Request for Certificate of Correction (1 pg.);

X Certificate of Correction (3 pgs. - in duplicate)

**Certificate**

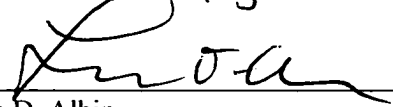
**AUG 08 2004**

**of Correction**

Please consider this a PETITION FOR EXTENSION OF TIME for a sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 13-4895. Triplicate copies of this sheet are enclosed.

**CERTIFICATE UNDER 37 C.F.R. §1.8:** The undersigned hereby certifies that this Transmittal Letter and the paper(s), as described hereinabove, are being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Attention Certificate of Correction Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 2 day of August, 2004.

MUETING, RAASCH & GEBHARDT, P.A.  
Customer Number: 26813

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AUG 10 2004



PATENT  
Docket No. 150.00720103

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Applicant(s): Cobbley et al. )  
Patent No.: 6,699,928 B2 )  
Issued: March 2, 2004 )  
For: ADHESIVE COMPOSITION FOR USE IN PACKAGING APPLICATIONS

**REQUEST FOR CERTIFICATE OF CORRECTION**

Attention Certificate of Correction Branch  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

A Certificate of Correction is requested to be issued correcting printing errors appearing in the above-identified United States patent. Two copies of the text noting the corrections for the Certificate are enclosed. Since none of the errors listed are due to Applicants' mistake, no fee is necessary for the Certificate. The corrections in the proposed Certificate of Correction do not involve such changes in the patent as would constitute new matter or would require reexamination.

Please mail the printed Certificate of Correction to the undersigned attorney.

Respectfully submitted for  
**Cobbley et al.**

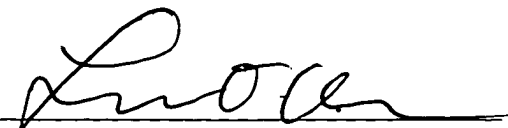
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Loren D. Albin

August 2, 2004  
Date

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PATENT NO.: 6,699,928 B2

DATED: March 2, 2004

INVENTOR(S): Cobbley et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In column 3, line 24, please insert a – . – after "composition";

In column 3, line 24, please start a new paragraph after "adhesive composition."  
Starting the new paragraph with –Another aspect of the present...–;

In column 4, lines 5-6, please delete "2oxy-ethyl" and insert –2-ethoxyethyl–;

In column 8, line 47, please delete "nonbasic" and insert – non-basic–;

In column 15, lines 62-64, please delete "about 5 kg of applied force. Heat is also applied at a temperature of about 200° C. or less. Typically, a bond forms in about 1 second or less." and insert,

–typically a rigid structure having a pattern therein and can be formed from a variety of conventional materials that do not chemically react with screen printing paste. The pattern included in the stencil 167 includes a plurality of apertures 177 separated by solid portions (not labeled) of the stencil, wherein the plurality of apertures correspond to the desired location for dispensing the instant setting adhesive composition on the die 144. A quantity of the instant setting adhesive composition 146' is dispensed on a solid portion of the stencil 167, although the exact amount of the instant setting adhesive composition is not critical. A flexible blade 175 is positioned near the quantity of the instant setting adhesive composition 146'. The flexible blade 175 moves in one direction, shown for example as arrow A so as to pull the quantity of the instant setting adhesive composition against the stencil. Thus, it is similar in operation to that of a squeegee. As the flexible blade 175 is drawn over the surface of the stencil 167, a portion of the instant setting adhesive composition 146' falls through the plurality of apertures 177 to form a layer of instant setting adhesive composition 146 in the discrete pattern corresponding to the plurality of apertures 177 in the stencil 167. Accordingly, because the instant setting adhesive composition can be

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applied at room temperature and sets to form a discrete pattern, stenciling is an advantageous method of application because special heating equipment is not required to apply the instant setting adhesive composition.

Furthermore, an instant setting adhesive composition could be deposited and patterned using a resist pattern with a solvent. This is sometimes referred to as a resist etch back. In general, such a resist etch back would involve patterning the adhesive composition with a patterned resist layer and then removing the resist with a suitable solvent, leaving the patterned instant setting adhesive composition.

Following or during the adhesive deposition process, the adhesive composition 146 is patterned such that streets (or zones) 152 are formed between the individual dice 144, such as by the methods described above. This is particularly useful for singulating the dice 144, e.g. saw cutting the dice. Preferably, these zones 152 are substantially free of adhesive 146, as shown in Figures 6 and 7. These streets 152 are also variously known in the art as scribe lines, saw lines, or avenues. With the streets 152 free of adhesive, the efficiency of the saw cutting procedure is unaffected by the adhesive layer 146. It is to be understood, however, that the invention can be practiced with adhesive located in the streets 152.

With respect to LOC packaging processes as shown at least in part in Figures 8-10A, in addition to the streets 152 preferably being essentially free of adhesive, the adhesive layer 146 is patterned such that the bond pads 154 (Fig. 8) for the dice 144 are also free of adhesive. As shown in Figure 8, this may be accomplished by patterning a substantially adhesive free area 156 around the bond pads 154. This may also be accomplished by a finer patterning of the adhesive layer 146 such that rather than having wide adhesive free areas, only the bond pads 154 are clear of adhesive (not shown).

With each die 144 coated with an instant setting adhesive composition 146, as shown in Figs. 8 and 9, the lead fingers 158, 160 of a leadframe can be attached to the die 144 by the application of heat and pressure, as indicated by pressure arrow 180,

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182, in Fig. 10A. Pressure may be applied by a suitable technique such as a movable arm pressing the assembly against a stationary platen. Under the effect of heat and pressure, the adhesive composition 146 is in effect sandwiched between the lead fingers 158, 160 and the die 144 to form an adhesive bond or layer therebetween. This firmly attaches the die 144 to the lead fingers 158, 160 for the subsequent encapsulation process.

As shown in Fig.10B, the die 144 includes bond pads 154 on one surface (typically the face surface). A back surface 151 is attached to lead fingers 158 with an instant setting adhesive composition 146. As described with respect to Fig. 10A, the lead fingers 158, 160 of a leadframe can be attached to the back surface 151 of the die 144 by the application of heat and pressure, as indicated by pressure arrow 180, 182. Again, under the effect of heat and pressure, the adhesive composition 146 is sandwiched between the lead fingers 158, 160 and the back surface 151 of the die 144 to form an adhesive bond or layer therebetween. This firmly attaches the die 144 to the lead fingers 158, 160 for the subsequent encapsulation process.

In forming a bond between any of the substrates described above with the instant setting adhesive composition as described herein, the pressure that is applied is typically about 5 kg of applied force. Heat is also applied at a temperature of about 200°C or less. Typically, a bond forms in about 1 second or less.-;

In column 17, line 43, please delete "methalkyl" and insert -methallyl-;

In column 17, line 67, please delete "crotyl" and insert -cresyl-;

In column 18, lines 23-24, please delete "a methalkyl group, and a 2-methoxymethyl group;" and insert - a methallyl group, a crotyl group, and a 2-methoxyethyl group;-.

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